



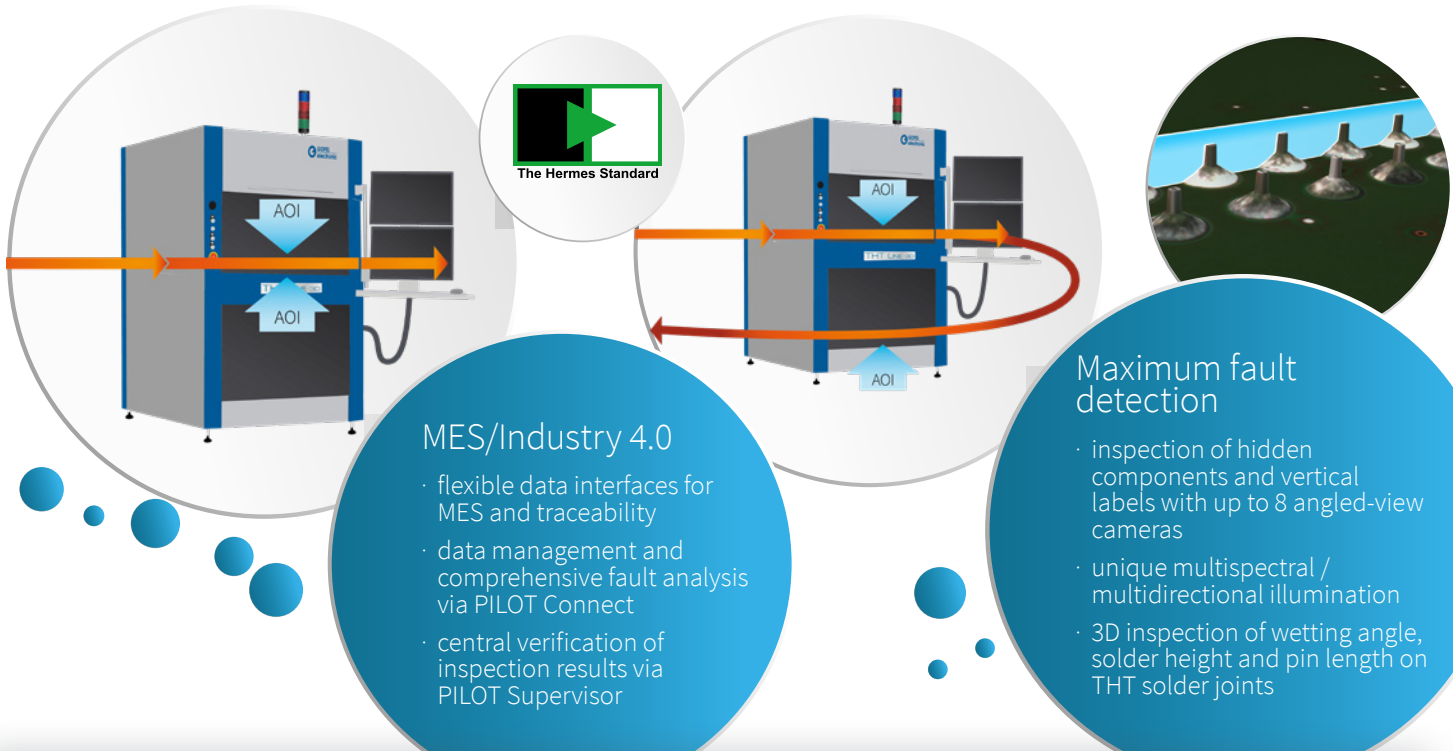
THT Line, THT Line·3D

AOI system for THT assemblies



- inspection of THT components, THT solder joints and wave soldered SMD components
- double-sided inspection of THT assemblies on the upper transport or lower return with or without carrier
- 3D inspection and pin height measurement for THT solder joints





Parameters	2D AOI module component side	3D AOI module component side	2D AOI module solder side	3D AOI module solder side
integration possibilities of AOI module	on upper conveyor	on upper conveyor	in the upper or lower conveyor	in the upper or lower conveyor
image capturing	orthogonal camera (telecentric), up to 8 angled-view cameras	3D camera module	orthogonal camera (telecentric)	3D camera module
max. inspection height	up to 80 mm	up to 35 mm		up to 35 mm
inspection speed	up to 100 cm ² /s			
max. inspection area	540 mm x 450 mm			
max. carrier size	up to 620 mm x 510 mm			
component clearance	above PCB: up to 135 mm (2D AOI) / up to 60 mm (3D AOI) below PCB: up to 40 mm			

Technical specifications of overall system	
power requirements	230 VAC / 2 kVA, compressed air at 6 bar, consumption < 20 l/h
transport system	belt conveyor for assemblies with or without carrier
transport direction	left-right, right-left, left-left, right-right
inline interface	SMEMA, Siemens, Sensor
dimensions (W x D x H)	1150 mm x 1300 mm x 1800 mm

Options
laser height measurement system
barcode, DMC or RFID reader system
system configuration for manual loading

Efficient use for production

- inspection of the solder side on the upper transport or the lower return
- AOI modules operating in parallel and independently in one system
- fully automated generation and optimization of test programs for THT solder joints with MagicClick